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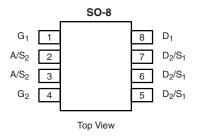




# Dual N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY							
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)				
Channel-1	- 30	$0.022$ at $V_{GS} = 10 \text{ V}$	6.3				
		0.030 at V <sub>GS</sub> = 4.5 V	5.4				
Channel-2		0.013 at V <sub>GS</sub> = 10 V	10				
		0.0185 at V <sub>GS</sub> = 4.5 V	8.6				

SCHOTTKY PRODUCT SUMMARY							
V <sub>DS</sub> (V)	V <sub>SD</sub> (V) Si (V) Diode Forward Voltage						
30	0.50 V at 1.0 A	2.0					



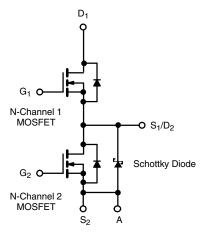
Ordering Information: Si4816DY-T1-E3 (Lead (Pb)-free)

Si4816DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- LITTLE FOOT® Plus Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC





<b>ABSOLUTE MAXIMUM RATIN</b>	<b>GS</b> $T_A = 25$	°C, unless	otherwise	e noted				
			Channel-1		Channel-2			
Parameter	Symbol	10 s	Steady State	10 s	Steady State	Unit		
Drain-Source Voltage	$V_{DS}$	30				V		
Gate-Source Voltage	$V_{GS}$	20						
O .: D : O (T 150.00)3	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	6.3	5.3	10	7.7		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		5.4	4.2	8.2	6.2		
Pulsed Drain Current	I <sub>DM</sub>	30		40		Α		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	1.3	0.9	2.2	1.15		
Avalanche Current <sup>b</sup>	1 0.1 mll	I <sub>AS</sub>	12		25			
Single Pulse Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AS</sub>		7.2		31.25	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	- P <sub>D</sub>	1.4	1.0	2.4	1.25	W	
	T <sub>A</sub> = 70 °C		0.9	0.64	1.5	0.8	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS										
			Channel-1		Channel-2		Schottky			
Parameter	Symbol	Тур.	Max.	Тур.	Max.	Тур.	Max.	Unit		
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	R <sub>thJA</sub>	72	90	43	53	48	60		
Maximum Junction-to-Ambient	Steady State	' 'thJA	100	125	82	100	80	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJC}$	51	63	25	30	28	35		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Starting date code W46BAA.



MOSFET SPECIFICATIONS $T_J = 25$ °C, unless otherwise notedParameterSymbolTest ConditionsMin.Typ.aMax.Un									
Static	Syllibol	rest conditions		IVIIII.	iyp.	IVIAA.	Oint		
Gate Threshold Voltage	I ,, I		Ch-1	0.8		2			
	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	Ch-2	1.0		3	V		
0 . 5		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 20 V	Ch-1			100	nA		
Gate-Body Leakage	I <sub>GSS</sub>		Ch-2			100			
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	Ch-1			1			
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	Ch-2			100	μΑ		
Zero date voltage Brain Garrent	.033	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	Ch-1			15	μπ		
			Ch-2			2000			
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	Ch-1	20			А		
Cir State Brain Santri	B(OII)		Ch-2	30					
		$V_{GS} = 10 \text{ V}, I_D = 6.3 \text{ A}$	Ch-1		0.018	0.022	Ω		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	Ch-2		0.0105	0.013			
Diam-Gource on Glate Hesistance	1 103(011)	$V_{GS} = 4.5 \text{ V}, I_D = 5.4 \text{ A}$	Ch-1		0.024	0.030	22		
		$V_{GS} = 4.5 \text{ V}, I_D = 8.6 \text{ A}$	Ch-2		0.015	0.0185			
Forward Transconductance <sup>b</sup>	g <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 6.3 \text{ A}$	Ch-1		17		S		
Tolward Harisconductance		$V_{DS} = 15 \text{ V}, I_D = 10 \text{ A}$	Ch-2		28				
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	$I_S = 1.3 \text{ A V}, V_{GS} = 0 \text{ V}$	Ch-1		0.7	1.1	V		
		I <sub>S</sub> = 1 A V, V <sub>GS</sub> = 0 V	Ch-2		0.47	0.5			
Dynamic <sup>a</sup>	T T		T T		<u> </u>	T	T		
Total Gate Charge	$Q_g$	Channel-1 $V_{DS} = 15 \text{ V, } V_{GS} = 5 \text{ V, } I_{D} = 6.3 \text{ A}$	Ch-1		8.0	12			
	9		Ch-2		15	23	nC		
Gate-Source Charge	$Q_{qs}$	Channel-2 $V_{DS} = 15 \text{ V, } V_{GS} = 5 \text{ V, } I_D = -10 \text{ A}$	Ch-1		1.75				
<u> </u>	95		Ch-2		5.3				
Gate-Drain Charge	$Q_{qd}$		Ch-1		3.2				
<u> </u>	94		Ch-2		4.6				
Gate Resistance	$R_{q}$		Ch-1	1.5		6.1	Ω		
	9		Ch-2	0.5	4.0	2.6			
Turn-On Delay Time	t <sub>d(on)</sub> t <sub>r</sub>	Channel-1 $V_{DD} = 15 \text{ V, R}_{L} = 15 \Omega$	Ch-1		10	20			
-			Ch-2		15	30	ns		
Rise Time  Turn-Off Delay Time		$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_q = 6 \Omega$	Ch-1		5	10			
		3 32. <b></b> 9	Ch-2		5	10			
		Channel-2	Ch-1		26	50			
	(* /	$V_{DD}$ = 15 V, $R_L$ = 15 $\Omega$	Ch-2		44	80			
Fall Time	t <sub>f</sub>	$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 6 \Omega$	Ch-1		8	16			
		I <sub>F</sub> = 1.3 A, dI/dt = 100 A/μs	Ch-2		12	24			
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	$I_F = 1.3 \text{ A, dl/dt} = 100 \text{ A/µs}$ $I_F = 2.2 \text{ A, dl/dt} = 100 \text{ µA/µs}$	Ch-1		30	60			
•		$I_F = \angle . \angle A$ , $uI/uI = IUU \mu A/\mu S$	Ch-2		32	70			

### Notes:

- a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

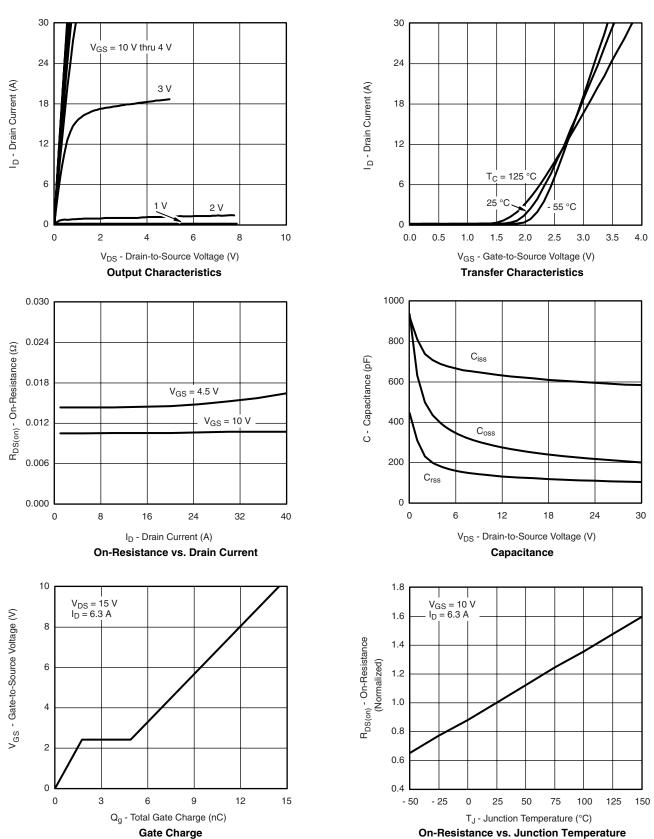
<b>SCHOTTKY SPECIFICATIONS</b> $T_J = 25$ °C, unless otherwise noted										
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit				
Forward Voltage Drop	V <sub>F</sub>	I <sub>F</sub> = 1.0 A		0.47	0.50	V				
		I <sub>F</sub> = 1.0 A, T <sub>J</sub> = 125 °C		0.36	0.42					
Maximum Reverse Leakage Current	I <sub>rm</sub>	V <sub>R</sub> = 30 V		0.004	0.100					
		V <sub>R</sub> = 30 V, T <sub>J</sub> = 100 °C		0.7	10	mA				
		V <sub>R</sub> = - 30 V, T <sub>J</sub> = 125 °C		3.0	20					
Junction Capacitance	C <sub>T</sub>	V <sub>R</sub> = 10 V		50		pF				

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





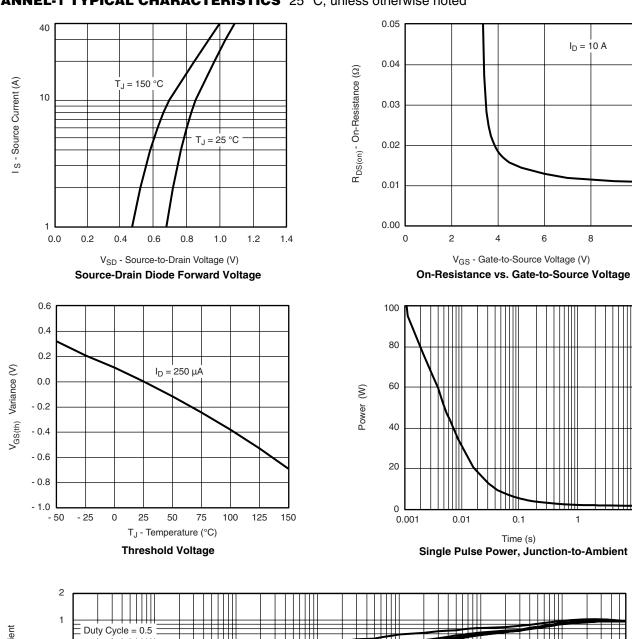
### CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

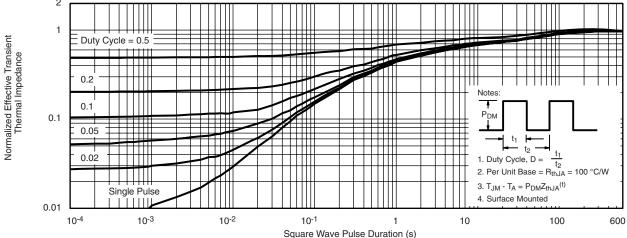


# VISHAY

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## CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

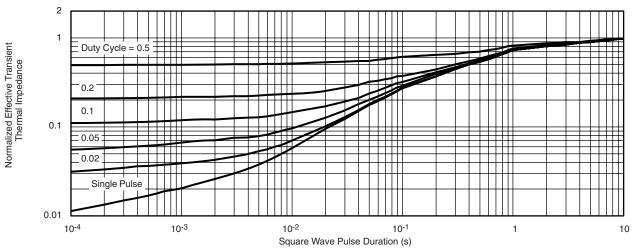




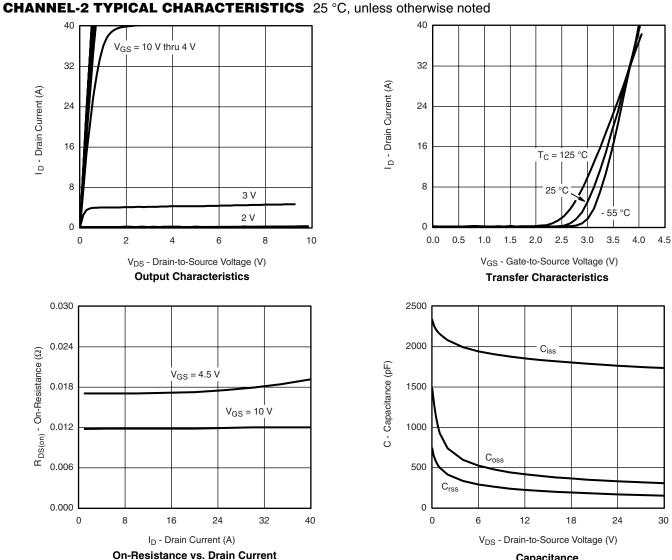
Normalized Thermal Transient Impedance, Junction-to-Ambient



### CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



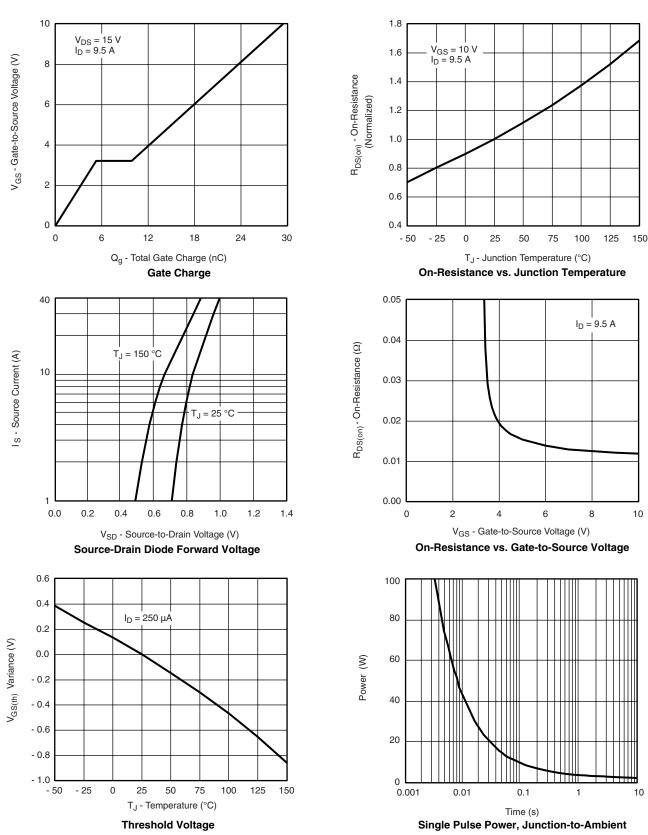
Normalized Thermal Transient Impedance, Junction-to-Foot



Capacitance

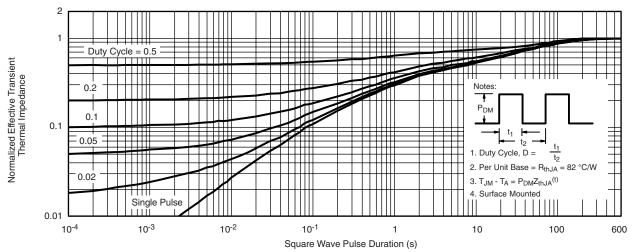
# VISHAY

## CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

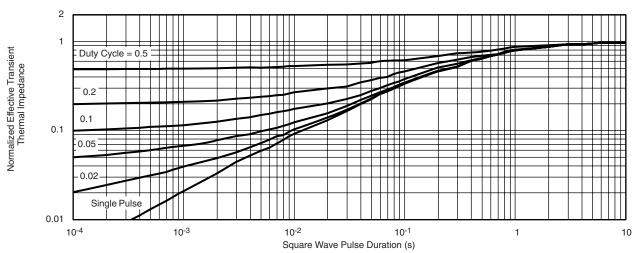




# **CHANNEL-2 TYPICAL CHARACTERISTICS** 25 $^{\circ}$ C, unless otherwise noted



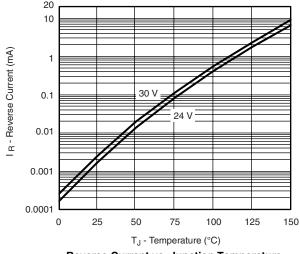
Normalized Thermal Transient Impedance, Junction-to-Ambient

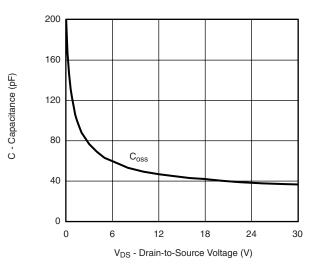


Normalized Thermal Transient Impedance, Junction-to-Foot



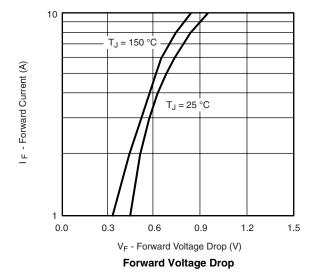
### SCHOTTKY TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





**Reverse Current vs. Junction Temperature** 





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